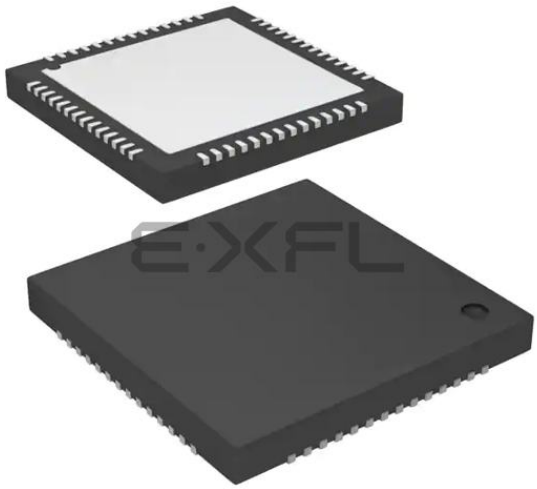

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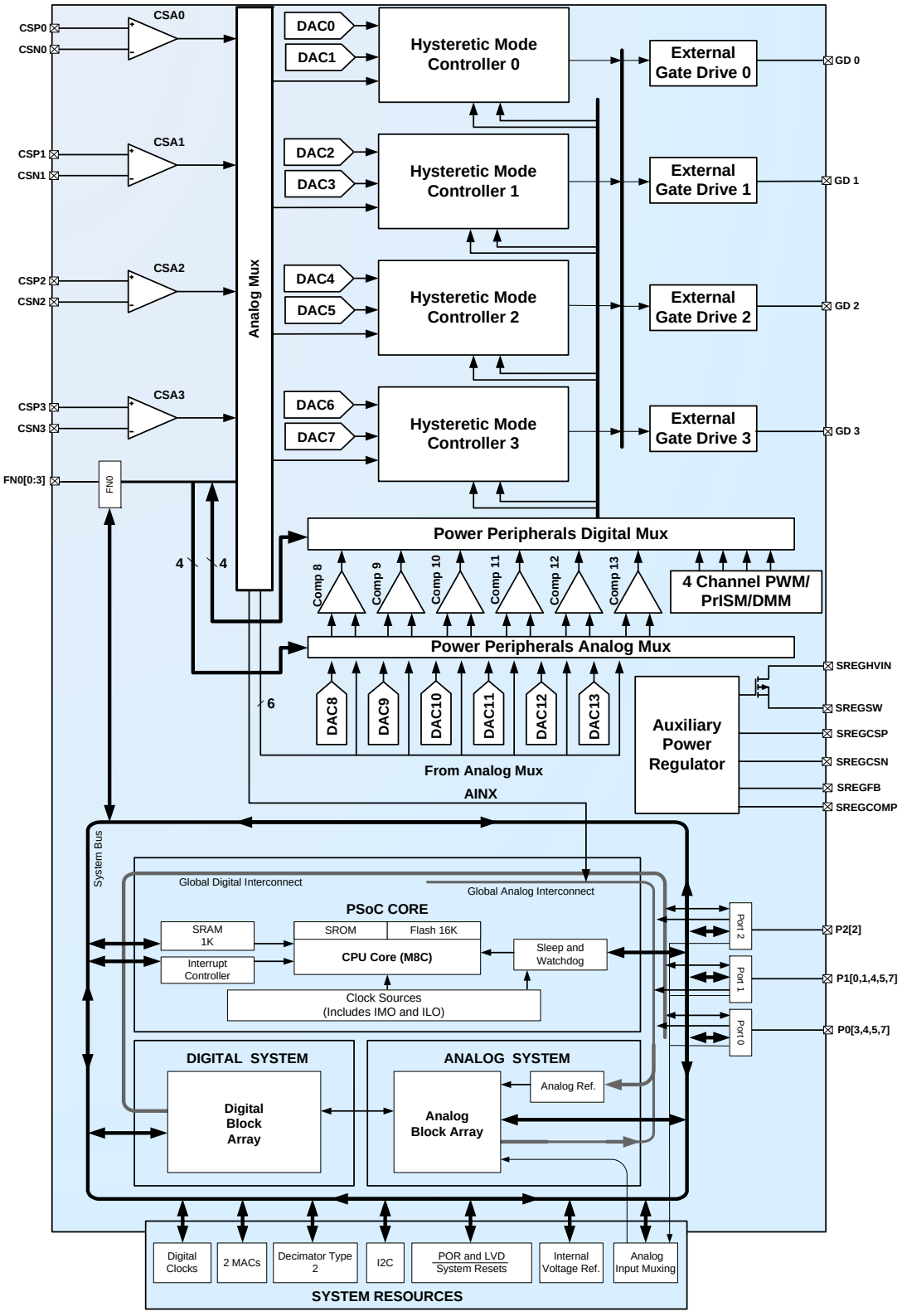
What Are Embedded - Microcontrollers - Application Specific?

Application-specific microcontrollers are engineered to

Details	
Product Status	Obsolete
Applications	Intelligent LED Driver
Core Processor	M8C
Program Memory Type	FLASH (16KB)
Controller Series	CY8CLED
RAM Size	1K x 8
Interface	DALI, DMX512, I²C, IrDA, SPI, UART/USART
Number of I/O	14
Voltage - Supply	4.75V ~ 5.25V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	56-VFQFN Exposed Pad
Supplier Device Package	56-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8cled04docd1-56ltxi

Figure 3-2. CY8CLED04G01 Logic Block Diagram



4. PowerPSoC® Functional Overview

The PowerPSoC family incorporates programmable system-on-chip technology with the best in class power electronics controllers and switching devices to create easy to use power-system-on-chip solutions for lighting applications.

All PowerPSoC family devices are designed to replace traditional MCUs, system ICs, and the numerous discrete components that surround them. PowerPSoC devices feature high performance power electronics including 1 ampere 2 MHz power FETs, hysteretic controllers, current sense amplifiers, and PrISM/PWM modulators to create a complete power electronics solution for LED power management. Configurable power, analog, digital, and interconnect circuitry enables a high level of integration in a host of industrial, commercial, and consumer LED lighting applications.

This architecture integrates programmable analog and digital blocks to enable you to create customized peripheral configurations that match the requirements of each individual application. Additionally, the device includes a 24 MHz CPU, Flash program memory, SRAM data memory, and configurable I/O in a range of convenient pinouts and packages.

The PowerPSoC architecture, as illustrated in the block diagrams, consists of five main areas: PSoC core, digital system, analog system, system resources, and power peripherals, which include power FETs, hysteretic controllers, current sense amplifiers, and PrISM/PWM modulators. Configurable global busing combines all of the device resources into a complete custom system. The PowerPSoC family of devices have 10-port I/Os that connect to the global digital and analog interconnects, providing access to eight digital blocks and six analog blocks.

5. Power Peripherals

PowerPSoC is designed to operate at voltages from 7 V to 32 V, drive up to 1 ampere of current using internal MOSFET switches, and over 1 ampere with external MOSFETs.

This family of devices (CY8CLED0xD/G0y) combines up to four independent channels of constant current drivers. These drivers feature hysteretic controllers with the Programmable System-on-Chip (PSoC) that contains an 8-bit microcontroller, configurable digital and analog peripherals, and embedded flash memory.

The CY8CLED0xD/G0y is the first product in the PowerPSoC family to integrate power peripherals to add further integration for your power electronics applications.The PowerPSoC family of intelligent power controller ICs are used in lighting applications that need traditional MCUs and discrete power electronics support. The power peripherals of the CY8CLED0xD/G0y include up to four 32 volt power MOSFETs with current ratings up to 1 ampere each. It also integrates gate drivers that enable applications to drive external MOSFETs for higher current and voltage capabilities. The controller is a programmable threshold hysteretic controller, with user-selectable feedback paths that uses the IC in current mode floating load buck, floating load buck-boost, and boost configurations.

5.1 Hysteretic Controllers

The PowerPSoC contains four hysteretic controllers. There is one hysteretic controller for each channel of the device.

The hysteretic controllers provide cycle by cycle switch control with fast transient response, which simplifies system design by requiring no external compensation. The hysteretic controllers include the following key features:

- Four independent channels
- DAC configurable thresholds
- Wide switching frequency range from 20 kHz to 2 MHz
- Programmable minimum on and off time
- Floating load buck, floating load buck-boost and boost topology controller

The reference inputs (REF_A and REF_B in Figure 5-1.) of the hysteretic controller are provided by the reference DACs as illustrated in the top level block diagram (see Figure 3-1. on page 3).

The hysteretic control function output is generated by comparing the feedback value to two thresholds. Going below the lower threshold turns the switch ON and exceeding the upper threshold turns the switch OFF as shown in Figure 5-1. The output current waveforms are shown in Figure 5-2.

The hysteretic controller also controls the minimum on-time and off-time. This circuit prevents oscillation at very high frequencies; which can be very destructive to output switches.

The output to the gate drivers is gated by the Trip, DIM and Enable signals. The Enable signal is a direct result of the enable bit in the control register for the hysteretic controller.

The Trip signal can be any digital signal that follows TTL logic (logic high and logic low). It is an active high input.

The DIM Modulation signal is the output of the dedicated modulators that are present in the power peripherals, or any other digital modulation signal.

Figure 5-1. Generating Hysteretic Control Function Output

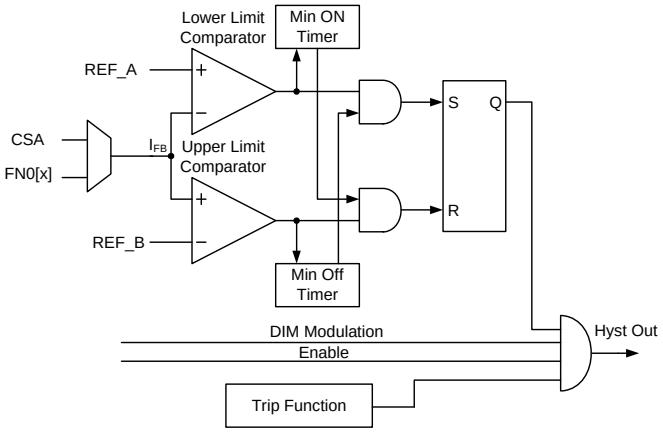
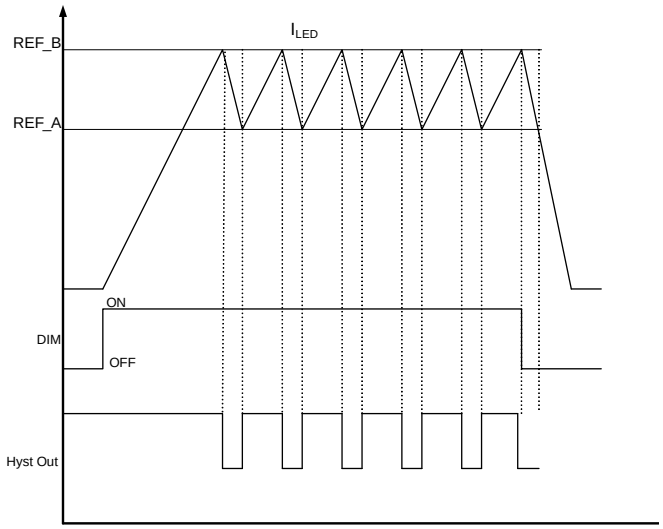


Figure 5-2. Current Waveforms



The minimum on-time and off-time circuits in the PowerPSoC prevent oscillations at very high frequencies, which can be very destructive to output switches.

5.2 Low Side N-Channel FETs

The internal low side N-Channel FETs are designed to enhance system integration. The low side N-Channel FETs include the following key features:

- Drive capability up to 1 A
- Switching times of 20 ns (rise and fall times) to ensure high efficiency (more than 90%)
- Drain source voltage rating 32 V
- Low $R_{DS(ON)}$ to ensure high efficiency
- Switching frequency up to 2 MHz

5.3 External Gate Drivers

These gate drivers enable the use of external FETs with higher current capabilities or lower $R_{DS(ON)}$. The external gate drivers directly drive MOSFETs that are used in switching applications. The gate driver provides multiple programmable drive strength steps to enable improved EMI management. The external gate drivers include the following key features:

- Programmable drive strength options (25%, 50%, 75%, 100%) for EMI management
- Rise and fall times at 55 ns with 4 nF load

5.4 Dimming Modulation Schemes

There are three dimming modulation schemes available with the PowerPSoC. The configurable modulation schemes are:

- Precise intensity signal modulation (PrISM)
- Delta Sigma modulation mode (DMM)
- Pulse-width modulation (PWM)

5.4.1 PrISM Mode Configuration

- High resolution operation up to 16 bits
- Dedicated PrISM module enables customers to use core PSoC digital blocks for other needs
- Clocking up to 48 MHz
- Selectable output signal density
- Reduced EMI

The PrISM mode compares the output of a pseudo-random counter with a signal density value. The comparator output asserts when the count value is less than or equal to the value in the signal density register.

5.4.2 DMM Mode Configuration

- High resolution operation up to 16 bits
- Configurable output frequency and delta sigma modulator width to trade off repeat rates versus resolution
- Dedicated DMM module enables customers to use PSoC digital blocks for other uses
- Clocking up to 48 MHz

The DMM modulator consists of a 12-bit PWM block and a 4-bit delta sigma modulator (DSM) block. The width of the PWM, the width of the DMM, and the clock defines the output frequency. The duty cycle of the PWM output is dithered by using the DSM block which has a user-selectable resolution up to 4 bits.

5.4.3 PWM Mode Configuration

- High resolution operation up to 16 bits
- User programmable period from 1 to 65535 clocks
- Dedicated PWM module enables customers to use core PSoC digital blocks for other use
- Interrupt on rising edge of the output or terminal count
- Precise PWM phase control to manage system current edges
- Phase synchronization among the four channels
- PWM output can be aligned to left, right, or center

The PWM features a down counter and a pulse width register. A comparator output is asserted when the count value is less than or equal to the value in the pulse width register.

5.5 Current Sense Amplifier

The high side current sense amplifiers provide a differential sense capability to sense the voltage across current sense resistors in lighting systems. The current sense amplifier includes the following key features:

- Operation with high common mode voltage to 32 V
- High common mode rejection ratio
- Programmable bandwidth to optimize system noise immunity

An off-chip resistor R_{sense} is used for high side current measurement as shown in Figure 5-3. on page 11. The output of the current sense amplifier goes to the power peripherals analog multiplexer where, you select the hysteretic controller to which

6. PSoC Core

The PSoC core is a powerful engine that supports a rich feature set. The core includes a CPU, memory, clocks, and configurable general purpose I/O(GPIO).

The M8C CPU core is a powerful processor with speeds up to 24 MHz, providing a four MIPS 8-bit Harvard architecture microprocessor. The CPU uses an interrupt controller with up to 20 vectors to simplify programming of real time embedded events. The program execution is timed and protected using the included sleep and watchdog timers (WDT) time and protect program execution.

Memory encompasses 16 K of flash for program storage, 1 K of SRAM for data storage, and up to 2 K of EEPROM emulated using the flash. Program flash uses four protection levels on blocks of 64 bytes, allowing customized software IP protection.

The PSoC device incorporates flexible internal clock generators, including a 24 MHz internal main oscillator (IMO) accurate to 4 percent over temperature and voltage. The 24 MHz IMO can also be doubled to 48 MHz for use by the digital system. A low power 32 kHz internal low-speed oscillator (ILO) is provided for the sleep timer and WDT. The clocks, together with programmable clock dividers (as a system resource), provide the flexibility to integrate almost any timing requirement into the PowerPSoC device.

PowerPSoC GPIOs provide connection to the CPU, digital, and analog resources of the device. Each pin's drive mode may be selected from eight options, allowing great flexibility in external interfacing. Every pin also has the capability to generate a system interrupt on high level, low level, and change from last read.

6.1 Digital System

The digital system contains eight digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user module references.

Digital peripheral configurations include:

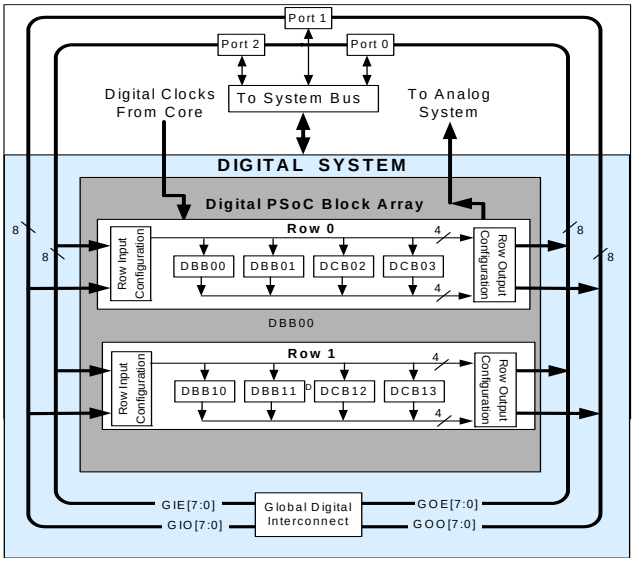
- DMX512
- Counters (8 to 32 bit)
- Timers (8 to 32 bit)
- UART 8-bit with selectable parity
- SPI master and slave
- I^2C master, slave, and multi-master
- Cyclical redundancy checker/generator (8 to 32 bit)
- IrDA
- Pseudo random sequence generators (8 to 32 bit)

Note The DALI interface is supported through the use of a combination of the above mentioned user modules. For more details on the exact configuration and an example project, refer to the application note, PowerPSoC Firmware Design Guidelines, Lighting Control Interfaces - AN51012.

The digital blocks can be connected to any GPIO through a series of global buses that route any signal to any pin. The buses also allow signal multiplexing and performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

There are four digital blocks in each row. This allows optimum choice of system resources for your application.

Figure 6-1. Digital System Block Diagram



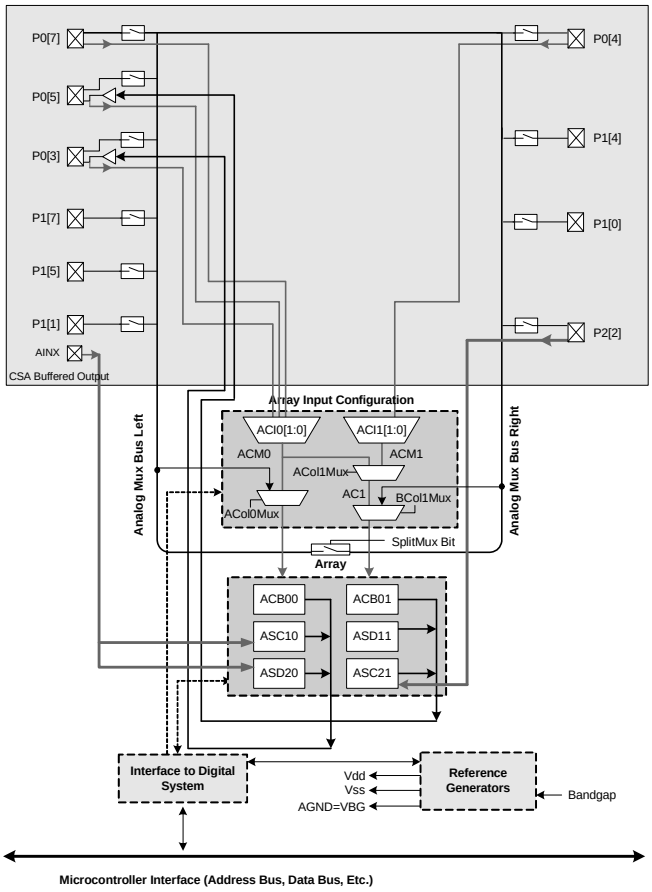
6.2 Analog System

The analog system contains six configurable blocks, each comprised of an opamp circuit allowing the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the more common PowerPSoC analog functions (most available as user modules) are:

- Analog-to-digital converters (up to 2, with 6 to 12-bit resolution, selectable as incremental, Delta Sigma, and SAR)
- Filters (2 and 4 pole band-pass, low-pass, and notch)
- Amplifiers (up to 2, with selectable gain to 48x)
- Instrumentation amplifiers (1 with selectable gain to 93x)
- Comparators (up to 2, with 16 selectable thresholds)
- DACs (up to 2, with 6 to 9-bit resolution)
- Multiplying DACs (up to 2, with 6 to 9-bit resolution)
- High current output drivers (two with 30 mA drive as a PSoC core resource)
- 1.3 V reference (as a system resource)
- Modulators
- Correlators
- Peak detectors
- Many other topologies possible

Analog blocks are arranged in two columns of three blocks each, which includes one continuous time (CT) and two switched capacitor (SC) blocks, as shown in Figure 6-2. on page 14.

Figure 6-2. Analog System Block Diagram



6.3 Analog Multiplexer System

The Analog Mux Bus connects to every GPIO pin in ports 0 to 2. Pins can be connected to the bus individually or in any combination. The bus also connects to the analog system for analysis with comparators and analog-to-digital converters. It can be split into two sections for simultaneous dual-channel processing. An additional analog input multiplexer provides a second path to bring Port 0 pins to the analog array.

Switch control logic enables selected pins to precharge continuously under hardware control. This enables capacitive measurement for applications such as touch sensing. Other multiplexer applications include:

- Track pad, finger sensing
- Crosspoint connection between any I/O pin combinations

Like other PSoC devices, PowerPSoC has specific pins allocated to the reference capacitor (Ref Cap) and modulation resistor (Mod resistor). These are indicated in the device pinouts (Section 13). For more details on capacitive sensing, see the design guide, Getting Started With CapSense. Apart from these, there are a number of application notes on Capacitive Sensing on the Cypress webbiest. The PowerPSoC Technical Reference Manual provides details on the analog system configuration that enables all I/Os in the device to be CapSense inputs.

6.4 Additional System Resources

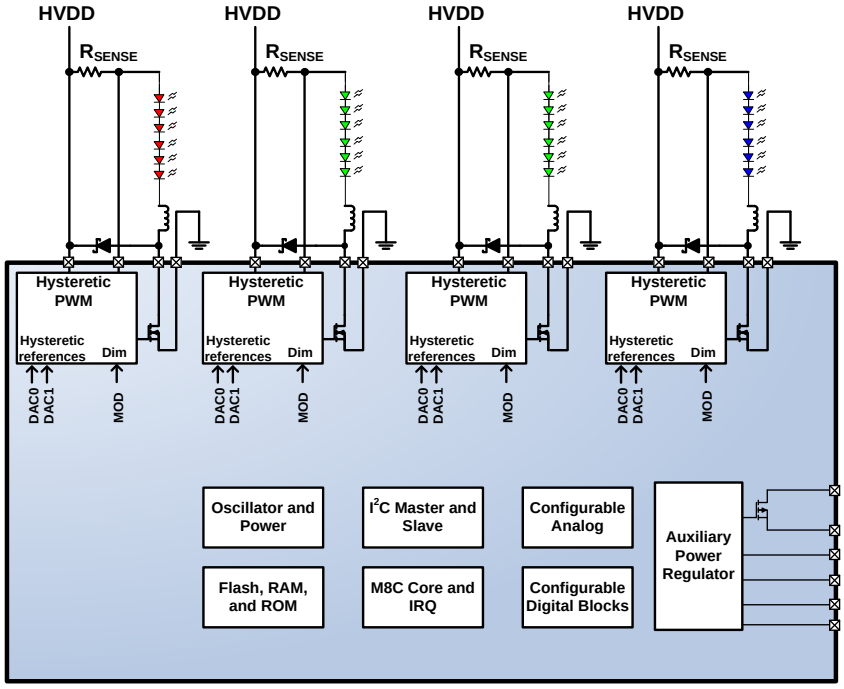
System resources provide additional capability useful in complete systems. Additional resources include a multiplier, decimator, low voltage detection, and power on reset. Brief statements describing the merits of each resource follow.

- Two multiply accumulates (MACs) provide fast 8-bit multipliers with 32-bit accumulate, to assist in both general math and digital filters.
- A decimator provides a custom hardware filter for digital signal processing applications including creation of delta sigma ADCs.
- Low-voltage detection (LVD) interrupts signal the application of falling voltage levels, while the advanced POR (power on reset) circuit eliminates the need for a system supervisor.
- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks can be routed to both the digital and analog systems. The designer can generate additional clocks using digital PSoC blocks as clock dividers.
- The I^2C module provides 100 and 400 kHz communication over two wires. Slave, master, and multi-master applications are supported.
- An internal 1.3 V reference provides an absolute reference for the analog system, including ADCs and DACs.
- Versatile analog multiplexer system.

7. Applications

The PowerPSoC family of devices can be used to add hysteretic current control capability to power applications. The devices can be used to control current in devices such as LEDs, heating elements, and solenoids. For LED applications, all high-brightness LEDs (HBLEDs) can be controlled using the PowerPSoC. The following figures show examples of applications in which the PowerPSoC family of devices adds intelligent power control for power applications.

Figure 7-1. LED Lighting with RGGB Color Mixing Configured as Floating Load Buck Converter



12.4 CY8CLED03D0x 56-Pin Part Pinout (without OCD)

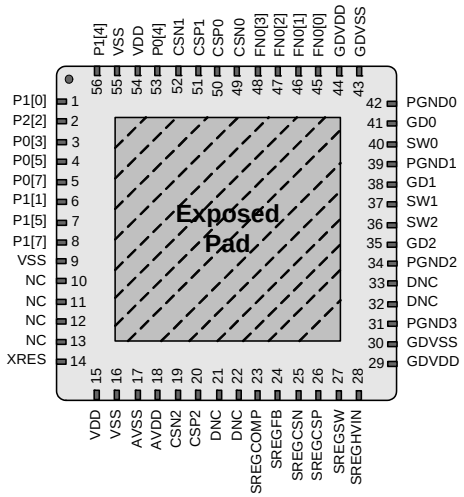
The CY8CLED03D01 and CY8CLED03D02 PowerPSoC devices are available with the following pinout information. Every port pin (labeled with a “P” and “FN0”) is capable of Digital I/O.

Table 12-4. CY8CLED03D0x 56-Pin Part Pinout (QFN)

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
1	I/O	I		P1[0]	GPIO/I2C SDA (Secondary)/ ISSP SDATA
2	I/O	I		P2[2]	GPIO/Direct Switch Cap connection
3	I/O	I/O		P0[3]	GPIO/Analog Input (Column 0)/ Analog Output (Column 0)
4	I/O	I/O		P0[5]	GPIO/Analog Input (Column 0)/ Analog Output (Column 1)/ Capsense Ref Cap
5	I/O	I		P0[7]	GPIO/Analog Input (Column 0)/ Capsense Ref Cap
6	I/O	I		P1[1]	GPIO/I2C SCL (Secondary)/ ISSP SCLK
7	I/O	I		P1[5]	GPIO/I2C SDA (Primary)
8	I/O	I		P1[7]	GPIO/I2C SCL (Primary)
9				V_{SS}	Digital Ground
10				NC	No Connect
11				NC	No Connect
12				NC	No Connect
13				NC	No Connect
14	I			XRES	External Reset
15				V_{DD}	Digital Power Supply
16				V_{SS}	Digital Ground
17				AV_{SS}	Analog Ground
18				AV_{DD}	Analog Power Supply
19			I	CSN2	Current Sense Negative Input - CSA2
20				CSP2	Current Sense Positive Input and Power Supply - CSA2
21				DNC[5]	Do Not Connect
22				DNC[5]	Do Not Connect
23				SREGCOMP	Voltage Regulator Error Amp Comp
24			I	SREGFB	Regulator Voltage Mode Feedback Node
25			I	SREGCSN	Current Mode Feedback Negative
26			I	SREGCSP	Current Mode Feedback Positive
27			O	SREGSW	Switch Mode Regulator OUT
28				SREGHVIN	Switch Mode Regulator IN
29				GDV_{DD}	Gate Driver Power Supply
30				GDV_{SS}	Gate Driver Ground
31				PGND3[6]	Power FET Ground 3
32				DNC[5]	Do Not Connect
33				DNC[5]	Do Not Connect
34				PGND2[6]	Power FET Ground 2
35			O	GD2	External Low Side Gate Driver 2
36				SW2	Power Switch 2
37				SW1	Power Switch 1
38			O	GD1	External Low Side Gate Driver 1
39				PGND1[6]	Power FET Ground 1
40				SW0	Power Switch 0
41			O	GD0	External Low Side Gate Driver 0
42				PGND0[6]	Power FETGround 0
43				GDV_{SS}	Gate Driver Ground

Figure 12-4. CY8CLED03D0x 56-Pin PowerPSoC Device

QFN Top View



*** Connect Exposed Pad to PGNDx**

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
44				GDV_{DD}	Gate Driver Power Supply
45			I/O	FN0[0]	Function I/O
46			I/O	FN0[1]	Function I/O
47			I/O	FN0[2]	Function I/O
48			I/O	FN0[3]	Function I/O
49			I	CSN0	Current Sense Negative Input 0
50				CSP0	Current Sense Positive Input and Power Supply - CSA0
51				CSP1	Current Sense Positive Input and Power Supply - CSA1
52			I	CSN1	Current Sense Negative Input 1
53	I/O	I		P0[4]	GPIO/Analog Input (Column 1) / Bandgap Output
54				V_{DD}	Digital Power Supply
55				V_{SS}	Digital Ground
56	I/O	I		P1[4]	GPIO / External Clock Input

Notes
5. Do Not Connect (DNC) pins must be left unconnected, or floating. Connecting these pins to power or ground may cause improper operation or failure of the device.
6. All PGNDx pins must be connected to the ground plane on the PCB irrespective of whether the corresponding PowerPSoC channel is used or not.

12.5 CY8CLED03G01 56-Pin Part Pinout (without OCD)

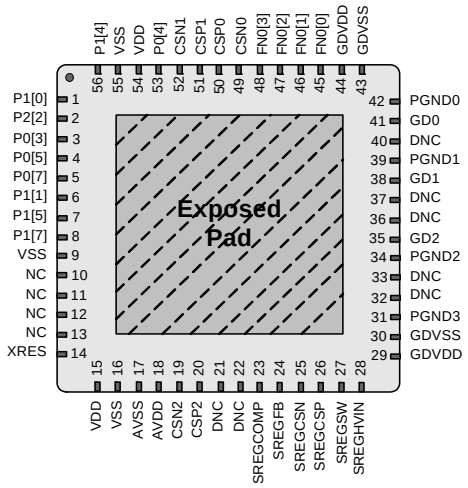
The CY8CLED03G01 PowerPSoC device is available with the following pinout information. Every port pin (labeled with a “P” and “FN0”) is capable of Digital I/O.

Table 12-5. CY8CLED03G01 56-Pin Part Pinout (QFN)

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
1	I/O	I		P1[0]	GPIO/I2C SDA (Secondary)/ ISSP SDATA
2	I/O	I		P2[2]	GPIO/Direct Switch Cap connection
3	I/O	I/O		P0[3]	GPIO/Analog Input (Column 0)/ Analog Output (Column 0)
4	I/O	I/O		P0[5]	GPIO/Analog Input (Column 0)/ Analog Output (Column 1)/ Capsense Ref Cap
5	I/O	I		P0[7]	GPIO/Analog Input (Column 0)/ Capsense Ref Cap
6	I/O	I		P1[1]	GPIO/I2C SCL (Secondary)/ ISSP SCLK
7	I/O	I		P1[5]	GPIO/I2C SDA (Primary)
8	I/O	I		P1[7]	GPIO/I2C SCL (Primary)
9				V_{SS}	Digital Ground
10				NC	No Connect
11				NC	No Connect
12				NC	No Connect
13				NC	No Connect
14	I			XRES	External Reset
15				V_{DD}	Digital Power Supply
16				V_{SS}	Digital Ground
17				AV_{SS}	Analog Ground
18				AV_{DD}	Analog Power Supply
19			I	CSN2	Current Sense Negative Input 2
20				CSP2	Current Sense Positive Input and Power Supply - CSA2
21				DNC[7]	Do Not Connect
22				DNC[7]	Do Not Connect
23				SREGCOMP	Voltage Regulator Error Amp Comp
24			I	SREGFB	Regulator Voltage Mode Feedback Node
25			I	SREGCSN	Current Mode Feedback Negative
26			I	SREGCSP	Current Mode Feedback Positive
27			O	SREGSW	Switch Mode Regulator OUT
28				SREGHVIN	Switch Mode Regulator IN
29				GDV_{DD}	Gate Driver Power Supply
30				GDV_{SS}	Gate Driver Ground
31				PGND3[8]	Power FET Ground 3
32				DNC[7]	Do Not Connect
33				DNC[7]	Do Not Connect
34				PGND2[8]	Power FET Ground 2
35			O	GD2	External Low Side Gate Driver 2
36				DNC[7]	Do Not Connect
37				DNC[7]	Do Not Connect
38			O	GD1	External Low Side Gate Driver 1
39				PGND1[8]	Power FET Ground 1
40				DNC[7]	Do Not Connect
41			O	GD0	External Low Side Gate Driver 0
42				PGND0[8]	Power FET Ground 0
43				GDV_{SS}	Gate Driver Ground

Figure 12-5. CY8CLED03G01 56-Pin PowerPSoC Device

QFN Top View



*** Connect Exposed Pad to PGNDx**

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
44				GDV_{DD}	Gate Driver Power Supply
45			I/O	FN0[0]	Function I/O
46			I/O	FN0[1]	Function I/O
47			I/O	FN0[2]	Function I/O
48			I/O	FN0[3]	Function I/O
49			I	CSN0	Current Sense Negative Input 0
50				CSP0	Current Sense Positive Input and Power Supply - CSA0
51				CSP1	Current Sense Positive Input and Power Supply - CSA1
52			I	CSN1	Current Sense Negative Input 1
53	I/O	I		P0[4]	GPIO/Analog Input (Column 1) / Bandgap Output
54				V_{DD}	Digital Power Supply
55				V_{SS}	Digital Ground
56	I/O	I		P1[4]	GPIO / External Clock Input

Notes
7. Do Not Connect (DNC) pins must be left unconnected, or floating. Connecting these pins to power or ground may cause improper operation or failure of the device.
8. All PGNDx pins must be connected to the ground plane on the PCB irrespective of whether the corresponding PowerPSoC channel is used or not.

12.6 CY8CLED02D01 56-Pin Part Pinout (without OCD)

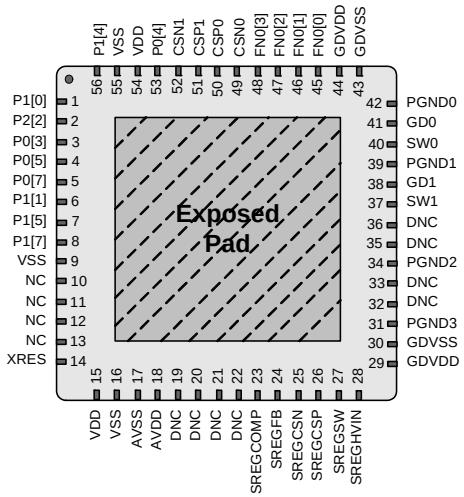
The CY8CLED02D01 PowerPSoC devices are available with the following pinout information. Every port pin (labeled with a “P” and “FN0”) is capable of Digital I/O.

Table 12-6. CY8CLED02D01 56-Pin Part Pinout (QFN)

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
1	I/O	I		P1[0]	GPIO/I2C SDA (Secondary)/ ISSP SDATA
2	I/O	I		P2[2]	GPIO/Direct Switch Cap connection
3	I/O	I/O		P0[3]	GPIO/Analog Input (Column 0)/ Analog Output (Column 0)
4	I/O	I/O		P0[5]	GPIO/Analog Input (Column 0)/ Analog Output (Column 1)/ Capsense Ref Cap
5	I/O	I		P0[7]	GPIO/Analog Input (Column 0)/ Capsense Ref Cap
6	I/O	I		P1[1]	GPIO/I2C SCLK (Secondary)/ ISSP SCLK
7	I/O	I		P1[5]	GPIO/I2C SDA (Primary)
8	I/O	I		P1[7]	GPIO/I2C SCL (Primary)
9				V_{SS}	Digital Ground
10				NC	No Connect
11				NC	No Connect
12				NC	No Connect
13				NC	No Connect
14	I			XRES	External Reset
15				V_{DD}	Digital Power Supply
16				V_{SS}	Digital Ground
17				AV_{SS}	Analog Ground
18				AV_{DD}	Analog Power Supply
19				DNC[9]	Do Not Connect
20				DNC[9]	Do Not Connect
21				DNC[9]	Do Not Connect
22				DNC[9]	Do Not Connect
23				SREGCOMP	Voltage Regulator Error Amp Comp
24			I	SREGFB	Regulator Voltage Mode Feedback Node
25			I	SREGCSN	Current Mode Feedback Negative
26			I	SREGCSP	Current Mode Feedback Positive
27			O	SREGSW	Switch Mode Regulator OUT
28				SREGHVIN	Switch Mode Regulator IN
29				GDV_{DD}	Gate Driver Power Supply
30				GDV_{SS}	Gate Driver Ground
31				PGND3[10]	Power FET Ground 3
32				DNC[9]	Do Not Connect
33				DNC[9]	Do Not Connect
34				PGND2[10]	Power FET Ground 2
35				DNC[9]	Do Not Connect
36				DNC[9]	Do Not Connect
37				SW1	Power Switch 1
38			O	GD1	External Low Side Gate Driver 1
39				PGND1[10]	Power FET Ground 1
40				SW0	Power Switch 0
41			O	GD0	External Low Side Gate Driver 0
42				PGND0[10]	Power FETGround 0
43				GDV_{SS}	Gate Driver Ground

Figure 12-6. CY8CLED02D01 56-Pin PowerPSoC Device

QFN Top View



*** Connect Exposed Pad to PGNDx**

Pin No.	Type			Name	Description
	Digital Rows	Analog Columns	Power Peripherals		
44				GDV_{DD}	Gate Driver Power Supply
45			I/O	FN0[0]	Function I/O
46			I/O	FN0[1]	Function I/O
47			I/O	FN0[2]	Function I/O
48			I/O	FN0[3]	Function I/O
49			I	CSN0	Current Sense Negative Input 0
50				CSP0	Current Sense Positive Input and Power Supply - CSA0
51				CSP1	Current Sense Positive Input and Power Supply - CSA1
52			I	CSN1	Current Sense Negative Input 1
53	I/O	I		P0[4]	GPIO/Analog Input (Column 1) / Bandgap Output
54				V_{DD}	Digital Power Supply
55				V_{SS}	Digital Ground
56	I/O	I		P1[4]	GPIO / External Clock Input

Notes
9. Do Not Connect (DNC) pins must be left unconnected, or floating. Connecting these pins to power or ground may cause improper operation or failure of the device.
10. All PGNDx pins must be connected to the ground plane on the PCB irrespective of whether the corresponding PowerPSoC channel is used or not.

13. Register General Conventions

13.1 Abbreviations Used

The register conventions specific to this section are listed in Table 13-1.

Table 13-1. Register Conventions

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

13.2 Register Naming Conventions

The register naming convention specific to the PSoC core section of PowerPSoC blocks and their registers is:

<Prefix>mn<Suffix>

where m = row index, n = column index

Therefore, ASD13CR3 is a register for an analog PowerPSoC block in row 1 column 3.

The register naming convention specific to the power peripheral section of PowerPSoC blocks and their registers is:

<Prefix>x<Suffix>
where x = number of channel

Therefore, CSA0_CR is a register for a power peripheral PowerPSoC block in for current sense amplifier, channel 0.

13.3 Register Mapping Tables

The PowerPSoC device has a total register address space of 512 bytes. The register space is also referred to as I/O space and is broken into two parts. The XIO bit in the flag register (CPU_F) determines which bank you are currently in. When the XIO bit is set, you are said to be in the “extended” address space or the “configuration” registers.

More detailed description of the registers are found in the PowerPSoC TRM. The TRM can be found at http://www.cypress.com/powerpsoc and clicking on the Technical Reference Manual link.

13.4 Register Map Bank 0 Table

Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW	DPWM0PCF	40	RW	ASC10CR0	80	RW	VDAC0_CR	C0	RW
PRT0IE	01	RW	DPWM0PDH	41	RW	ASC10CR1	81	RW	VDAC0_DR0	C1	RW
PRT0GS	02	RW	DPWM0PDL	42	RW	ASC10CR2	82	RW	VDAC0_DR1	C2	RW
PRT0DM2	03	RW	DPWM0PWH	43	RW	ASC10CR3	83	RW		C3	
PRT1DR	04	RW	DPWM0PWL	44	RW	ASD11CR0	84	RW	VDAC1_CR	C4	RW
PRT1IE	05	RW	DPWM0PCH	45	RW	ASD11CR1	85	RW	VDAC1_DR0	C5	RW
PRT1GS	06	RW	DPWM0PCL	46	RW	ASD11CR2	86	RW	VDAC1_DR1	C6	RW
PRT1DM2	07	RW	DPWM0GCFG	47	RW	ASD11CR3	87	RW		C7	
PRT2DR	08	RW	DPWM1PCF	48	RW		88		VDAC2_CR	C8	RW
PRT2IE	09	RW	DPWM1PDH	49	RW		89		VDAC2_DR0	C9	RW
PRT2GS	0A	RW	DPWM1PDL	4A	RW		8A		VDAC2_DR1	CA	RW
PRT2DM2	0B	RW	DPWM1PWH	4B	RW		8B			CB	
FN0DR	0C	RW	DPWM1PWL	4C	RW		8C		VDAC3_CR	CC	RW
FN0IE	0D	RW	DPWM1PCH	4D	RW		8D		VDAC3_DR0	CD	RW
FN0GS	0E	RW	DPWM1PCL	4E	RW		8E		VDAC3_DR1	CE	RW
FN0DM2	0F	RW	DPWM1GCFG	4F	RW		8F			CF	
	10		DPWM2PCF	50	RW	ASD20CR0	90	RW	CUR_PP	D0	RW
	11		DPWM2PDH	51	RW	ASD20CR1	91	RW	STK_PP	D1	RW
	12		DPWM2PDL	52	RW	ASD20CR2	92	RW		D2	
	13		DPWM2PWH	53	RW	ASD20CR3	93	RW	IDX_PP	D3	RW
	14		DPWM2PWL	54	RW	ASC21CR0	94	RW	MVR_PP	D4	RW
	15		DPWM2PCH	55	RW	ASC21CR1	95	RW	MVW_PP	D5	RW
	16		DPWM2PCL	56	RW	ASC21CR2	96	RW	I2C_CFG	D6	RW
	17		DPWM2GCFG	57	RW	ASC21CR3	97	RW	I2C_SCR	D7	#
PDMUX_S1	18	RW	DPWM3PCF	58	RW		98		I2C_DR	D8	RW
PDMUX_S2	19	RW	DPWM3PDH	59	RW		99		I2C_MSCR	D9	#
PDMUX_S3	1A	RW	DPWM3PDL	5A	RW		9A		INT_CLR0	DA	RW
PDMUX_S4	1B	RW	DPWM3PWH	5B	RW		9B		INT_CLR1	DB	RW
PDMUX_S5	1C	RW	DPWM3PWL	5C	RW	VDAC6_CR	9C	RW	INT_CLR2	DC	RW
PDMUX_S6	1D	RW	DPWM3PCH	5D	RW	VDAC6_DR0	9D	RW	INT_CLR3	DD	RW
	1E		DPWM3PCL	5E	RW	VDAC6_DR1	9E	RW	INT_MSK3	DE	RW
CHBOND_CR	1F	RW	DPWM3GCFG	5F	RW		9F		INT_MSK2	DF	RW
DBB00DR0	20	#	AMX_IN	60	RW	VDAC4_CR	A0	RW	INT_MSK0	E0	RW
DBB00DR1	21	W	AMUX_CFG	61	RW	VDAC4_DR0	A1	RW	INT_MSK1	E1	RW
DBB00DR2	22	RW		62		VDAC4_DR1	A2	RW	INT_VC	E2	RC
DBB00CR0	23	#	ARF_CR	63	RW		A3		RES_WDT	E3	W
DBB01DR0	24	#	CMP_CR0	64	#	VDAC5_CR	A4	RW	DEC_DH	E4	RC
DBB01DR1	25	W	ASY_CR	65	#	VDAC5_DR0	A5	RW	DEC_DL	E5	RC
DBB01DR2	26	RW	CMP_CR1	66	RW	VDAC5_DR1	A6	RW	DEC_CR0	E6	RW
DBB01CR0	27	#	PAMUX_S1	67	RW		A7		DEC_CR1	E7	RW
DCB02DR0	28	#	PAMUX_S2	68	RW	MUL1_X	A8	W	MUL0_X	E8	W
DCB02DR1	29	W	PAMUX_S3	69	RW	MUL1_Y	A9	W	MUL0_Y	E9	W
DCB02DR2	2A	RW	PAMUX_S4	6A	RW	MUL1_DH	AA	R	MUL0_DH	EA	R
DCB02CR0	2B	#		6B		MUL1_DL	AB	R	MUL0_DL	EB	R
DCB03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCB03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCB03DR2	2E	RW	TMP_DR2	6E	RW	ACC1_DR3	AE	RW	ACC0_DR3	EE	RW
DCB03CR0	2F	#	TMP_DR3	6F	RW	ACC1_DR2	AF	RW	ACC0_DR2	EF	RW
DBB10DR0	30	#	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBB10DR1	31	W	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBB10DR2	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
DBB10CR0	33	#	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBB11DR0	34	#	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBB11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBB11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DBB11CR0	37	#	ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12DR0	38	#	DPWM0PCFG	78	RW	RDI1RI	B8	RW		F8	
DCB12DR1	39	W	DPWM1PCFG	79	RW	RDI1SYN	B9	RW		F9	
DCB12DR2	3A	RW	DPWM2PCFG	7A	RW	RDI1IS	BA	RW		FA	
DCB12CR0	3B	#	DPWM3PCFG	7B	RW	RDI1LT0	BB	RW		FB	
DCB13DR0	3C	#	DPWMINTFLG	7C	RW	RDI1LT1	BC	RW		FC	
DCB13DR1	3D	W	DPWMINTMSK	7D	RW	RDI1RO0	BD	RW	DAC_D	FD	RW
DCB13DR2	3E	RW	DPWMSYNC	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCB13CR0	3F	#		7F			BF		CPU_SCR0	FF	#

14.2 Operating Temperature

Symbol	Description	Min	Typ	Max	Units	Notes
T_A	Ambient temperature	–40 –40	– –	+85 +105	°C °C	$T_J \le 115$ °C (Industrial rated) $T_J \le 125$ °C (extended temperature rated)
T_J	Junction temperature	–40 –40	– –	+115 +125	°C °C	Industrial rated Extended Temperature rated

15. Electrical Characteristics

15.1 System Level

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \le 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \le 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

Table 15-1. System Level Operating Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
f_{SW}	Circuit switching frequency range for hysteretic control loop	0.02	–	2	MHz	
$t_{D,MAX}$	Maximum delay time from CSA input to FET state change	– –	– –	100 115	ns ns	HV_{DD} = 24 V, I_D = 1 A, f_{SW} = 2 MHz (Industrial rated) HV_{DD} = 24 V, I_D = 1 A, f_{SW} = 2 MHz (Extended Temperature rated)
D	Output duty cycle for hysteretic controllers	5	–	95	%	f_{SW} < 0.25 MHz
E	Power converter efficiency	90	95	–	%	HV_{DD} = 24 V, I_D = 1 A, f_{SW} = 2 MHz

15.2 Chip Level

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \le 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \le 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

Note See the *PowerPSoC Technical Reference Manual* for more information on the DPWMxPCF register

Table 15-2. Chip Level DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{DD}, AV_{DD}, GDV_{DD}	Digital, analog, and gate driver supply voltage range	4.75	–	5.25	V	All should be powered from the same source.
HV_{DD}	Power converter high voltage supply range	7	–	32	V	
HV_{PINS}	Voltage range for the CSPx and SREGHVIN pins	7	–	32	V	Not all pins need to be at the same voltage level.
IV_{DD}	Supply current (V_{DD} pins), IMO = 24 MHz	–	16	50	mA	Conditions are V_{DD} = 5 V, T_J = 25 °C, CPU = 3 MHz, SYSCLK doubler disabled, VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 93.75 kHz, analog power = off.
I_AV_{DD}	Supply current (AV_{DD} pin)	–	–	25	mA	Conditions are V_{DD} = 5 V, T_J = 25 °C,

15.3 Power Peripheral Low Side N-Channel FET

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \leq 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \leq 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

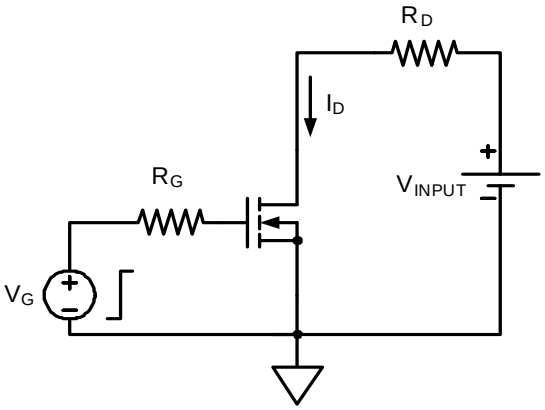
Table 15-4. Low Side N-Channel FET DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{DS}	Operating drain to source voltage	–	–	32	V	
$V_{DS,INST}$	Instantaneous drain source voltage	–	–	36	V	
I_D	Average drain current	– –	– –	1 0.5	A A	CY8CLED04/3/2/1D01 devices CY8CLED04/3D02 devices
I_{DMAX}	Maximum instantaneous repetitive pulsed current	– –	– –	3 1.5	A A	Less than 33% duty cycle for an average current of 1 A, f_{SW} = 0.1 MHz. CY8CLED04/3/2/1D01 devices Less than 33% duty cycle for an average current of 0.5 A, f_{SW} = 0.1 MHz. CY8CLED04/3D02 devices
$R_{DS(ON)}$	Drain to source ON resistance	– –	– –	0.5 1	Ω Ω	I_D = 1 A, GDV_{DD} = 5 V, T_J = 25 °C CY8CLED04/3/2/1D01 devices I_D = 0.5 A, GDV_{DD} = 5 V, T_J = 25 °C CY8CLED04/3D02 devices
I_{DSS}	Switching node to PGND leakage	– –	– –	10 250	µA µA	T_J = 25 °C T_J = 115 °C (Industrial rated) and T_J = 125 °C (Extended Temperature rated)
I_{SFET}	Supply current per channel - FET (internal gate driver)	–	–	6.25	mA	f_{SW} = 2 MHz

Table 15-5. Low Side N-Channel FET AC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
t_R	Rise time	–	–	20	ns	I_D = 1 A, R_D = 32 Ω
t_F	Fall time	–	–	20	ns	I_D = 1 A, R_D = 32 Ω

Figure 15-2. Low Side N-Channel FET Test Circuit for I_{DSS}, $t_{R, and}$ t_F



15.7 Power Peripheral Current Sense Amplifier

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \leq 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \leq 125$ °C for Extended Temperature rated devices. Typical parameters apply to V_{DD} of 5 V and HV_{DD} of 32 V at 25 °C. These are for design guidance only.

Table 15-12. Current Sense Amplifier DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{ICM}	Input common mode voltage operating range	7	–	32	V	Either terminal of the amplifier must not exceed this range for functionality
$V_{ICM(Tolerant)}$	Non functional operating range	0	–	32		Absolute maximum rating for V_{SENSE} should never be exceeded. See Absolute Maximum Ratings on page 30
V_{SENSE}	Input differential voltage range	0	–	150	mV	
$I_{S,CSA}$	Supply current - CSA	–	–	1	mA	Enabling CSA causes an incremental draw of 1 mA on the AV_{DD} rail.
I_{BIASP}	Input bias current (+)	–	–	600	µA	
I_{BIASN}	Input bias current (-)	–	–	1	µA	
PSR_{HV}	Power supply rejection (CSP pin)	–	–	–25	dB	$f_{SW} < 2$ MHz
K	Gain	19.7 19.4	20 20	20.3 20.6	V/V V/V	V_{SENSE} = 50 mV to 130 mV (Industrial rated) V_{SENSE} = 50 mV to 130 mV (Extended Temperature rated)
V_{IOS}	Input offset	–	2	4	mV	V_{SENSE} = 50 mV to 130 mV
C_{IN_CSP}	CSP input capacitance	–	–	5	pF	
C_{IN_CSN}	CSN input capacitance	–	–	2	pF	

Table 15-13. Current Sense Amplifier AC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
t_{SETTLE}	Output settling time to 1% of final value	–	–	5	µs	
$t_{POWERUP}$	Power up time to 1% of final value	–	–	5	µs	

Figure 15-4. Current Sense Amplifier Timing Diagram

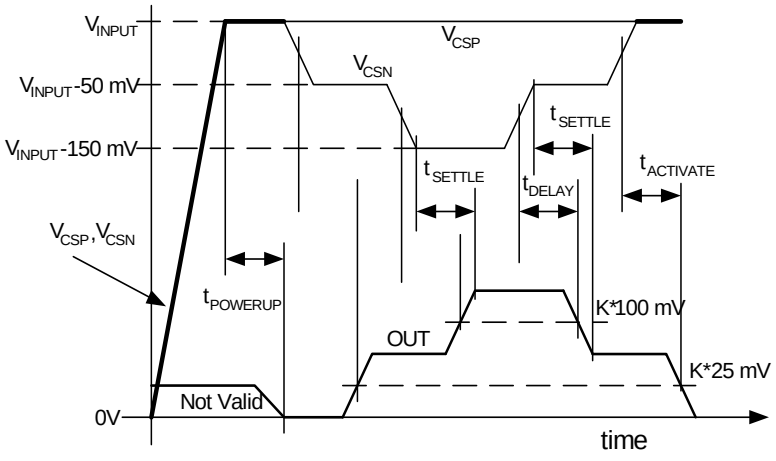


Table 15-18. Built-in Switching Regulator DC Specifications (continued)

Symbol	Description	Min	Typ	Max	Units	Notes
$Load_{REG}$	Load regulation	–	1	–	mV	V_{REGIN} = 24 V, I_{LOAD} = 2.5 mA to 250 mA
PSRR	Power supply rejection ratio	–	–60	–	dB	V_{RIPPLE} = 0.2 * V_{REGIN}, f_{RIPPLE} = 1 kHz to 10 kHz
E_{BSR}	Built-in switching regulator efficiency	80	–	–	%	V_{REGIN} = 24 V, I_{LOAD} = 250 mA

Table 15-19. Built-in Switching Regulator AC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
f_{SW}	Switching frequency	0.956	1	1.04	MHz	–
t_{RESP}	Response time to within 0.5% of final value	–	10	–	µs	–
t_{SU}	Startup time	–	–	1	ms	–
t_{PD}	Power down time	–	–	100	µs	–
t_{PD_ACT}	Time from power down to active mode	–	–	1	ms	–
t_{ACT_PD}	Time from active mode to power down mode	–	–	50	µs	–
SR_{REGIN}	Ramp rate for the SREGHVIN pin	–	–	32	V/µs	See Absolute Maximum Ratings on page 30

Table 15-20. Built-in Switching Regulator Recommended Components

Component Name	Value	Unit	Notes
R_{fb1}	2	kΩ	Tolerance 1% and 0.05-W rated or better
R_{fb2}	0.698	kΩ	Tolerance 1% and 0.05-W rated or better
C_{comp}	2200	pF	Tolerance 20% and 6.3-V rated or better
R_{comp}	20	kΩ	Tolerance 5% and 0.05-W rated or better
L	47	µH	Tolerance 20% or better, Saturation current rating of 1.5 A or higher
R_{sense}	0.5	Ω	Tolerance 1% and 0.05 W (I_{LOAD} = 0.250 A) rated or better
C_1	10	µF	Ceramic, X7R grade, Minimum ESR of 0.1 Ω, 6.3-V rated
C_{in}	1	µF	Ceramic, X7R grade, 50-V rated (V_{REGIN} = 32 V)
D1	40/0.5	V/A	Schottky diode - Reverse voltage 40 V, average rectified forward current 0.5 A (V_{REGIN} = 32 V)

Note If the built-in switching regulator is not being used in a design, it must be configured as per the following instructions to ensure it is disabled in a safe state.

SREGFB: 5 V

SREGCSN: 5 V

SREGCSP: 5 V

SREGCOMP: Floating

SREGHVIN: ≥ VDD rail

SREGSW: Floating/Tie to SREGHVIN

If the switching regulator is disabled through wiring its input pins (as previously explained) then it must be disabled through software as well (bit SREG_TST[0] = 1), which is set in the Global Resources in the Interconnect View of PSoC Designer.

15.12 PSoC Core Operational Amplifier Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \le 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \le 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

The Operational Amplifier is a component of both the Analog Continuous Time PSoC blocks and the Analog Switched Capacitor PSoC blocks. The guaranteed specifications are measured in the Analog Continuous Time PSoC block.

Table 15-23. Operational Amplifier DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{OSOA}	Input offset voltage (absolute value) Power = low, opamp bias = high Power = medium, opamp bias = high Power = high, opamp bias = high	 – – – – – –	 1.6 1.6 1.3 1.3 1.2 1.2	 10 15 8 13 7.5 12	 mV mV mV mV mV mV	 Industrial rated Extended temperature rated Industrial rated Extended temperature rated Industrial rated Extended temperature rated
TCV_{OSOA}	Average input offset voltage drift	–	7.0	35.0	µV / °C	
I_{EBOA}	Input leakage current (Port 0 analog pins)	–	20	–	pA	Gross tested to 1 µA.
C_{INOA}	Input capacitance (Port 0 analog pins)	–	4.5	9.5	pF	T_J = 25 °C.
V_{CMOA}	Common mode voltage range Common mode voltage range (high power or high opamp bias)	0.0 0.5	– –	V_{DD} V_{DD} – 0.5	V V	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
G_{OLOA}	Open loop gain Power = low, opamp bias = high Power = medium, opamp bias = high Power = high, opamp bias = high	 60 60 80	 – – –	 – – –	 dB dB dB	–
$V_{OHIGHOA}$	High output voltage swing (internal signals) Power = low, opamp bias = high Power = medium, opamp bias = high Power = high, opamp bias = high	 V_{DD} – 0.2 V_{DD} – 0.2 V_{DD} – 0.5	 – – –	 – – –	 V V V	–
V_{OLOWOA}	Low output voltage swing (internal signals) Power = low, opamp bias = high Power = medium, opamp bias = high Power = high, opamp bias = high	 – – –	 – – –	 0.2 0.2 0.5	 V V V	–
I_{SOA}	Supply current (including associated analog output buffer) Power = low, opamp bias = low Power = low, opamp bias = high Power = medium, opamp bias = low Power = medium, opamp bias = high Power = high, opamp bias = low Power = high, opamp bias = high	 – – – – – –	 400 500 800 1200 2400 4600	 800 900 1000 1600 3200 6400	 µA µA µA µA µA µA	–
$PSRR_{OA}$	Supply voltage rejection ratio	52	80	–	dB	$V_{SS} \le V_{IN} \le (V_{DD} – 2.25)$ or $(V_{DD} – 1.25\ V) \le V_{IN} \le V_{DD}$.

15.15 PSoC Core Analog Reference

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \leq 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \leq 125$ °C for extended temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

The guaranteed specifications are measured through the Analog Continuous Time PSoC blocks. The power levels for AGND refer to the power of the analog continuous Time PSoC block. The power levels for RefHi and RefLo refer to the Analog Reference Control register. The limits stated for AGND include the offset error of the AGND buffer local to the Analog Continuous Time PSoC block. Reference control power is high.

Table 15-29. Analog Reference DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
BG	Bandgap voltage reference	1.28 1.27	1.30 1.30	1.32 1.33	V V	Industrial rated Extended Temperature rated
–	AGND = $V_{DD}/2$[16]	$V_{DD}/2 - 0.04$ $V_{DD}/2 - 0.02$	$V_{DD}/2 - 0.01$ $V_{DD}/2$	$V_{DD}/2 + 0.007$ $V_{DD}/2 + 0.02$	V V	Industrial rated Extended Temperature rated
–	AGND = 2 x BandGap[16]	2 x BG – 0.048	2 x BG – 0.030	2 x BG + 0.024	V	
–	AGND = BandGap[16]	BG – 0.009	BG + 0.008	BG + 0.016	V	
–	AGND = 1.6 x BandGap[16]	1.6 x BG – 0.022	1.6 x BG – 0.010	1.6 x BG + 0.018	V	
–	AGND Block to Block Variation (AGND = $V_{DD}/2$)[16]	–0.034	0.000	0.034	V	
–	RefHi = $V_{DD}/2$ + BandGap	$V_{DD}/2$ + BG – 0.10	$V_{DD}/2$ + BG	$V_{DD}/2$ + BG + 0.10	V	
–	RefHi = 3 x BandGap	3 x BG – 0.06	3 x BG	3 x BG + 0.06	V	
–	RefHi = 3.2 x BandGap	3.2 x BG – 0.112	3.2 x BG	3.2 x BG + 0.076	V	
–	RefLo = $V_{DD}/2$ – BandGap	$V_{DD}/2$ – BG – 0.04 $V_{DD}/2$ – BG – 0.06	$V_{DD}/2$ – BG + 0.024 $V_{DD}/2$ – BG	$V_{DD}/2$ – BG + 0.04 $V_{DD}/2$ – BG + 0.06	V V	Industrial rated Extended Temperature rated
–	RefLo = BandGap	BG – 0.06	BG	BG + 0.06	V	

15.16 PSoC Core Analog Block

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \leq 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \leq 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

Table 15-30. Analog Block DC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{CT}	Resistor unit value (continuous time)	–	12.2	–	kΩ	
C_{SC}	Capacitor unit value (switched capacitor)	–	80	–	fF	

Notes
16. AGND tolerance includes the offsets of the local buffer in the PSoC block. Bandgap voltage is 1.3 V ± 0.02 V.

Table 15-33. Programming AC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
t_{RSCLK}	Rise time of SCLK	1	–	20	ns	–
t_{FSCLK}	Fall time of SCLK	1	–	20	ns	–
t_{SSCLK}	Data set up time to falling edge of SCLK	40	–	–	ns	–
t_{HSCLK}	Data hold time from falling edge of SCLK	40	–	–	ns	–
f_{SCLK}	Frequency of SCLK	0	–	8	MHz	–
t_{ERASEB}	Flash erase time (block)	–	10	–	ms	–
t_{WRITE}	Flash block write time	–	40	–	ms	–
t_{DSCLK}	Data out delay from falling edge of SCLK	–	–	50	ns	–
$t_{ERASEALL}$	Flash erase time (bulk)	–	40	–	ms	Erase all blocks and protection fields immediately
$t_{PROGRAM\_HOT}$	Flash block erase + flash block write time	–	–	100[19]	ms	0 °C ≤ Tj ≤ 100 °C
$t_{PROGRAM\_COLD}$	Flash block erase + flash block write time	–	–	200[19]	ms	–40 °C ≤ Tj ≤ 0 °C

15.19 PSoC Core Digital Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V, $T_J \le 115$ °C for Industrial rated devices and 4.75 V to 5.25 V, $T_J \le 125$ °C for Extended Temperature rated devices. Typical parameters apply to 5 V at 25 °C. These are for design guidance only.

Table 15-34. Digital Block AC Specifications

Function	Description	Min	Typ	Max	Units	Notes
Timer	Capture pulse width	50[20]	–	–	ns	–
	Input frequency, no capture	–	–	49.92	MHz	–
	Input frequency, with capture	–	–	24.96	MHz	–
Counter	Enable pulse width	50[20]	–	–	ns	–
	Input frequency, no enable input	–	–	49.92	MHz	–
	Input frequency, enable input	–	–	24.96	MHz	–
Dead Band	Kill pulse width:					–
	Asynchronous restart mode	20	–	–	ns	–
	Synchronous restart mode	50[20]	–	–	ns	–
	Disable mode	50[20]	–	–	ns	–
	Input frequency	–	–	49.92	MHz	–
CRCPRS (PRS Mode)	Input clock frequency	–	–	49.92	MHz	–
CRCPRS (CRC Mode)	Input clock frequency	–	–	24.96	MHz	–
SPIM	Input clock frequency	–	–	8.32	MHz	Maximum data rate at 4.1 MHz due to 2 x over clocking.
SPIS	Input clock frequency	–	–	4.16	MHz	–
	Width of SS_ Negated between transmissions	50[20]	–	–	ns	–
Transmitter	Input clock frequency	–	–	24.96	MHz	Maximum data rate at 3.08 MHz due to 8 x over clocking.
	Input clock frequency with $V_{DD} \ge 4.75$ V, 2 stop bits	–	–	49.92	MHz	Maximum data rate at 6.15 MHz due to 8 x over clocking.
Receiver	Input clock frequency	–	–	24.96	MHz	Maximum data rate at 3.08 MHz due to 8 x over clocking.
	Input clock frequency with $V_{DD} \ge 4.75$ V, 2 stop bits	–	–	49.92	MHz	Maximum data rate at 6.15 MHz due to 8 x over clocking.

Notes
19. For the full industrial range, you must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at http://www.cypress.com under Application Notes for more information.
20. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

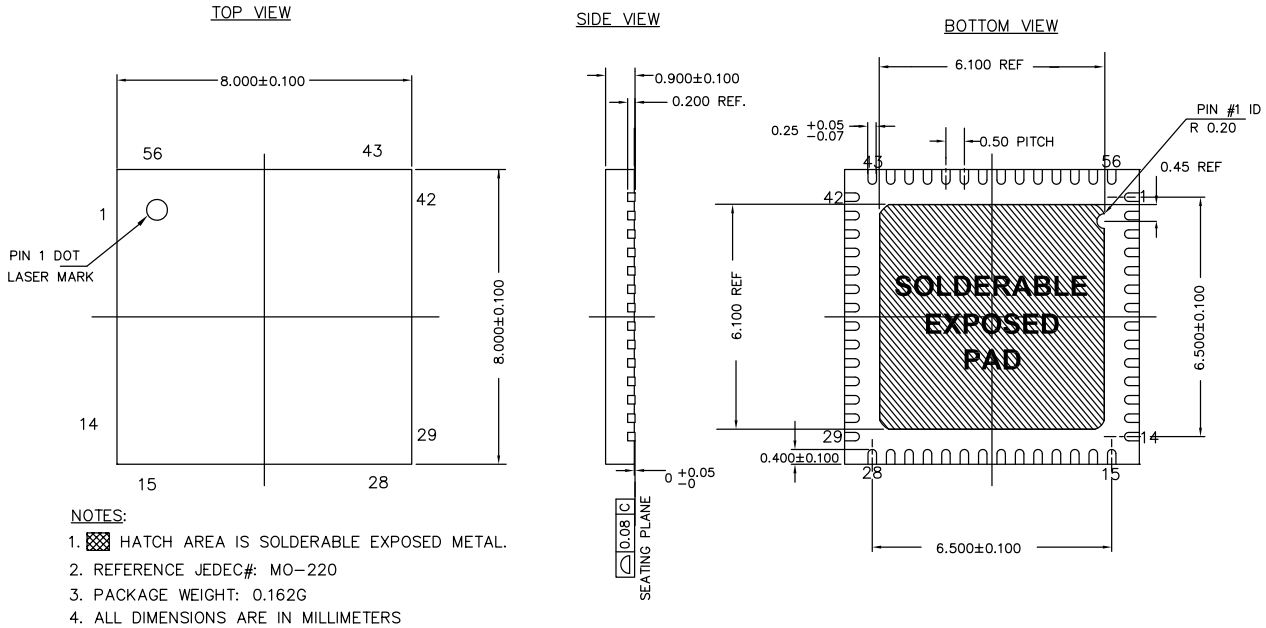
17. Packaging Information

Packaging Dimensions

This section illustrates the package specification for the CY8CLED04D0X, CY8CLED04G01, CY8CLED03D0X, CY8CLED03G01, CY8CLED02D01, and CY8CLED01D01 along with the thermal impedance for the package and solder reflow peak temperatures.

Important Note For information on the preferred dimensions for mounting QFN packages, see the following Application Note at http://www.amkor.com/products/notes_papers/MLFAppNote.pdf.

Figure 17-1. 56-Pin QFN (8 × 8 × 1.0 mm)



51-85187 *G

17.1 Thermal Impedance

Package	Typical θ_{JA} [22]
56 QFN[23]	16.6 °C/W

17.2 Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

Package	Minimum Peak Temperature[24]	Maximum Peak Temperature
56 QFN	240 °C	260 °C

Notes

22. $T_J = T_A + POWER \times \theta_{JA}$
23. To achieve the thermal impedance specified for the QFN package, the center thermal pad should be soldered to the PCB ground plane. The thermal model for Cypress's PowerPSoC family was simulated using a JESD51-7 standard FR4 PCB with four metal layers, 2 oz copper weight on outer layers, and 1 oz on inner layers. Thermal via array below the device is laid out according to package manufacturers' recommendations.
24. Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are 220 ± 5 °C with Sn-Pb or 245 ± 5 °C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.

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